

Title (en)

PROCESS AND ASSEMBLY FOR ADDITIVE MANUFACTURING OF COMPONENTS BY MATERIAL EXTRUSION

Title (de)

VERFAHREN UND ANORDNUNG ZUR ADDITIVEN FERTIGUNG VON BAUTEILEN MITTELS MATERIALEXTRUSION

Title (fr)

PROCÉDÉ ET DISPOSITIF DESTINÉS À LA FABRICATION ADDITIVE DE PIÈCES PAR EXTRUSION DE MATIÈRE

Publication

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Application

EP 22727781 A 20220503

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Abstract (en)

[origin: WO2022233831A1] The invention relates to a process and an assembly for additive manufacturing of components by material extrusion, wherein the components (1) are built up layerwise from a component material which is applied atop a carrier (10) layer by layer in a viscous state. In the process, the component material applied in each case as layer (8), in synchrony with application, is treated in the still-viscous state with at least one laser beam (3) directed onto a lateral boundary of the layer (8), preferably to achieve smoothing of unevenness on surfaces of the component (1). The process allows manufacturing of components by material extrusion with reduced surface roughness even on invisible surfaces, without any need for post-processing.

IPC 8 full level

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